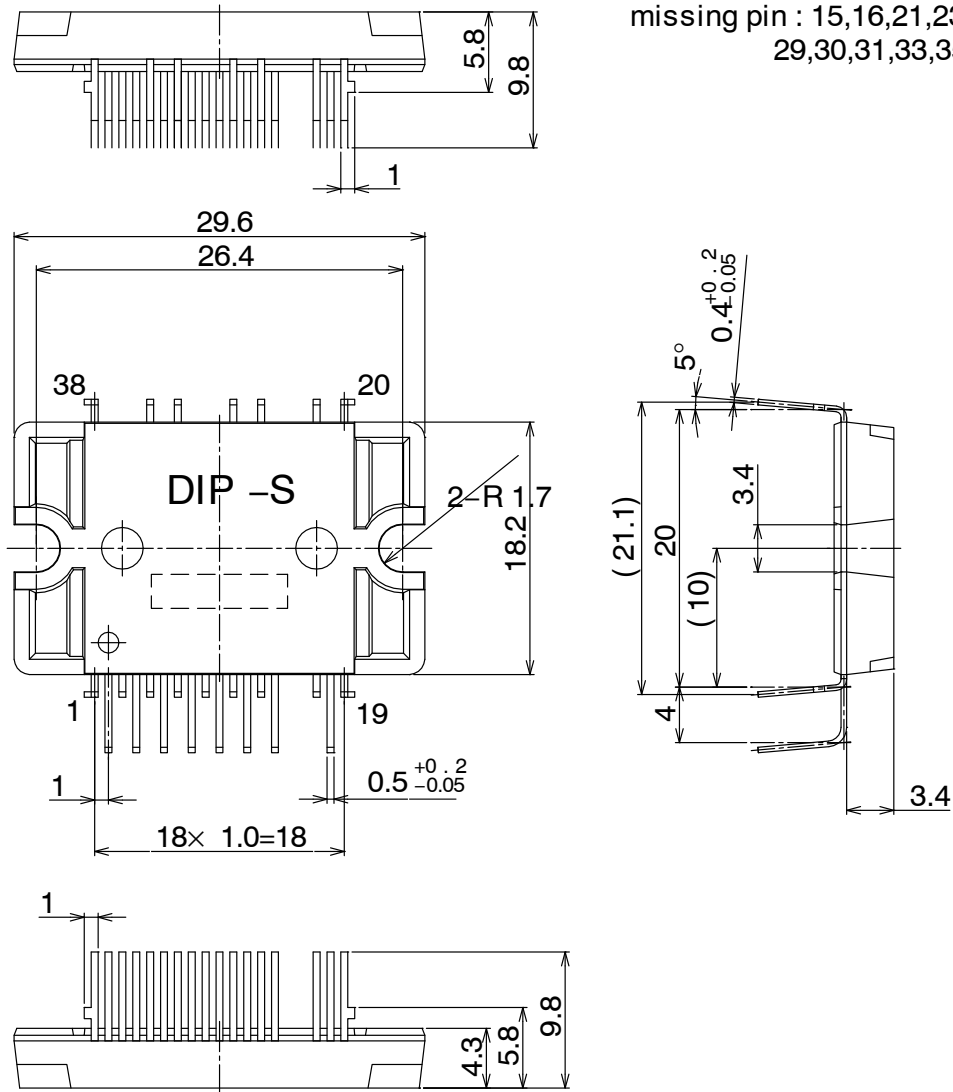


MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

HYBRID INTEGRATED MODULE / DIP-S
CASE MODBF
ISSUE 0

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